

# **Product Compliance Declaration**

Please see www.molex.com for the most up-to-date information.

#### **Contact Information**

Name Molex Product Compliance E-Mail Product.Compliance@molex.com

#### **Part Information**

Part Number 0353621650 Part Weight 0.834G

Part Name 2.0 W/B Conn. Wafer Assy

# **Product Composition**

Name	Туре	CAS Number	Proportion (% Total)	Mass (Grams)	
2.0 W/B Conn. Wafer Assy	Assembly		100	0.834	
2.0 W/B Conn. Wafer	Component		73.1415	0.61	
PA66-FR(30)	Material		73.1415	0.61	
PA66	Substance		63.0845	0.526125	
Flame Retardant, ISO 1043-4 FR(30)	Substance		5.8513	0.0488	
Further Additives, not to declare	Substance	system	0.7314	0.0061	
Pigment portion, not to declare	Substance	system	0.5486	0.004575	
Antimonytrioxide	Substance	1309-64-4	2.9257	0.0244	
0.5 SQ 8.8mm WIRE PIN PLATED	Assembly		26.8585	0.224	
0.5 SQ 8.8mm WIRE PIN UN-PLATED	Component		26.8585	0.224	
Yellow Brass 66% Unplated	Material		26.8585	0.224	
Copper	Substance	7440-50-8	17.7938 0.1484		
Zinc (metal)	Substance	7440-66-6	9.0647	0.0756	

#### Form Rev - F

Limitation of this Product Compliance Declaration: This declaration is based on the state of knowledge and belief of Molex as of the date that it is provided. Molex bases its knowledge and belief on information provided by numerous sources, including third parties, and in certain circumstances laboratory test results. Molex has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and substances. Molex represents that to the best of its knowledge that the information provided in this declaration is accurate. Molex's sole liability shall be to either replace the product or refund the purchase price of the product if it does not meet the requirement of this declaration.

#### **ROHS Declaration Information**

Regulatory Revision EU 2015/863

Compliance Status Compliant

**Contained Substances Exceeding Threshold** 

None

**Exemptions** 

None

## **REACH-SVHC Declaration Information**

**Regulatory Revision** D(2020)9139-DC (19 Jan 2021)

**Contained Substances Exceeding Threshold** 

None

# **GADSL Declaration Information**

Regulatory Revision GADSL imported from IMDS

# **Contained Substances Exceeding Threshold**

Substance Group	Substance Location	Threshold (PPM)	Concentration (PPM)	Intentionally Added
lead	C2680	*Note	250	Yes
Antimonytrioxide	PA66-FR(30)	*Note	50,000	Yes
copper	C2680	*Note	660,000	Yes

<sup>\*</sup>Note: For GADSL substance declarable/prohibited threshold values, please reference http://www.gadsl.org/

#### **Exemptions**

Part Name	Exemption			
C2680	44 Concentration within acceptable GADSL limits			

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# **HFLH Declaration Information**

Regulatory Revision IEC 61249-2-21

# **Contained Substances Exceeding Threshold**

None

# **China ROHS Declaration Information**

Part Number 0353621650							
Part Name 2.0 W/B Conn. Wafer Assy	<b>(e)</b>						
Part Information			Ha	zardous S	Substance	es	
Components		Lead	Mercury	Cadmium	Hex. Chromium	PBB	PBDE
2.0 W/B Conn. Wafer Assy		0	0	0	0	0	0
2.0 W/B Conn. Wafer		0	0	0	0	0	0
0.5 SQ 8.8mm WIRE PIN PLATED		0	0	0	0	0	0
0.5 SQ 8.8mm WIRE PIN UN-PLATED		0	0	0	0	0	0

## **Process Information**

Component Plating / Surface Finish	MSn
Termination Base Alloy	Brass
Solder Alloy	SnAgCu
Process Capability	N/A
Maximum Exposure Time (seconds)	N/A
Maximum Process Temperature (C)	N/A
Maximum Cycles at Reflow Temperature	N/A
J-STD-020 Moisture Sensitivity Level	N/A

Mar 24, 2021

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